

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	8698998
<b>Application Number:</b>	09523990
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	6138
<b>Title of Invention:</b>	Method of manufacture and identification of semiconductor chip marked for identification with internal marking indicia and protection thereof by non-black layer and device produced thereby
<b>First Named Inventor/Applicant Name:</b>	Mou-Shiung Lin
<b>Customer Number:</b>	89518
<b>Filer:</b>	Dennis Alan Duchene/Ashley Campbell
<b>Filer Authorized By:</b>	Dennis Alan Duchene
<b>Attorney Docket Number:</b>	085027-0026
<b>Receipt Date:</b>	25-OCT-2010
<b>Filing Date:</b>	13-MAR-2000
<b>Time Stamp:</b>	20:53:30
<b>Application Type:</b>	Utility under 35 USC 111(a)

### Payment information:

Submitted with Payment	yes
Payment Type	Deposit Account
Payment was successfully received in RAM	\$940
RAM confirmation Number	9701
Deposit Account	502624
Authorized User	

The Director of the USPTO is hereby authorized to charge indicated fees and credit any overpayment as follows:

Charge any Additional Fees required under 37 C.F.R. Section 1.16 (National application filing, search, and examination fees)

Charge any Additional Fees required under 37 C.F.R. Section 1.17 (Patent application and reexamination processing fees)

Charge any Additional Fees required under 37 C.F.R. Section 1.19 (Document supply fees)

Charge any Additional Fees required under 37 C.F.R. Section 1.20 (Post Issuance fees)

Charge any Additional Fees required under 37 C.F.R. Section 1.21 (Miscellaneous fees and charges)

## File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/Message Digest	Multi Part /.zip	Pages (if appl.)
1	Transmittal Letter	085027_0026_tm.pdf	22225 35af365034e2bb8d80f044dc6300286725eb1ef5	no	1

### Warnings:

### Information:

2	Request for Continued Examination (RCE)	085027_0026_rce.pdf	37324 a897052d5df3cb5551dd6fc54e0b9931d5bf76	no	1
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### Warnings:

This is not a USPTO supplied RCE SB30 form.

### Information:

3	Transmittal Letter	085027_0026_ids.pdf	23396 8aa5e52b89c8a6443d610ae6c24bb1c3b36986d9	no	2
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### Warnings:

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4	Information Disclosure Statement (IDS) Filed (SB/08)	085027_0026_idslist.pdf	63696 576ec1a1f070809855b8594d75c341b1de169700	no	3
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### Information:

This is not an USPTO supplied IDS fillable form

5	Request for Corrected Filing Receipt	085027_0026_FRequest.pdf	24145 f70adf28a72214d9d8e9a8ec0a4237d3a76925e8	no	2
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### Warnings:

### Information:

6		085027_0026_amendment.pdf	85899 6ee7fb5199b64327b4d47996760df76fa58ae066	yes	12
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### Multipart Description/PDF files in .zip description

	Document Description	Start	End
	Amendment Submitted/Entered with Filing of CPA/RCE	1	1
	Claims	2	4

	Applicant Arguments/Remarks Made in an Amendment			5	12			
<b>Warnings:</b>								
<b>Information:</b>								
7	NPL Documents	1.pdf	2254221 072127b124142b87d48b36305577e00d7f2 81092	no	4			
<b>Warnings:</b>								
<b>Information:</b>								
8	NPL Documents	2.pdf	3696109 daa31204b1d9d203a708a79ef619df46550 68174	no	9			
<b>Warnings:</b>								
<b>Information:</b>								
9	NPL Documents	3.pdf	4517666 1a340bcb7c9b1547370da4bc4129a0cd8aa aeb74	no	7			
<b>Warnings:</b>								
<b>Information:</b>								
10	NPL Documents	4.pdf	885848 789f5c75db4f5367e2064f35e1853c2a9776 ebb5	no	6			
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<b>Information:</b>								
11	NPL Documents	5.pdf	717153 6ea9c2af4c3f93c0d5e8d84fcc64bb8318ee e28a	no	5			
<b>Warnings:</b>								
<b>Information:</b>								
12	NPL Documents	6_HU_Copper_Polyimide.pdf	436455 60f30badcc448865be25da92121b117fce2 67a05	no	7			
<b>Warnings:</b>								
<b>Information:</b>								
13	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 8132037f7462423e7e041a4f39e24a5e4578 ab27	no	8			
<b>Warnings:</b>								
<b>Information:</b>								
14	NPL Documents	8_LEE_Effect_of_ESD_layout_on_the_assembly_yield.pdf	889090 a726022251835ff4d292326de7bc282d5944 1d614	no	4			
<b>Warnings:</b>								
<b>Information:</b>								

15	NPL Documents	9_YEOH_ESD_effects_on_power_supply_clamps.pdf	226994 ab71bc6a4d8720a9b8f6ef947e4dc5e395 eebb5	no	4
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16	NPL Documents	10_EDELSTEIN_Full_copper_wiring.pdf	1205963 9501660bd4c4309f18b1797ed0026a/b2bc 14322	no	4
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17	NPL Documents	11_VENKATESAN_A_High_performance_1_8V.pdf	618169 7bc331a4bbe29891fc13105b6c5bc7609f2c 568d	no	4
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18	NPL Documents	12_JENEI_HighQ_Inductors.pdf	279415 1749e7bdbf20e8e3ccb6d074bc3723f8cf b831	no	3
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19	NPL Documents	13_GROVES_HighQ_Inductors_in_a_SiGE_BiCMOS_process.pdf	420788 8e26f2f669459e3ce07d15bd587c4a335999 fa0e	no	4
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20	NPL Documents	14_SAKRAN_implementation_of_65nm.pdf	1254646 3b466f954664fc7184e733083683/d22ae0 8c5a1	no	3
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21	NPL Documents	15_KUMAR_Intel_ISSCC_2009_paper_on_power_on_chip.pdf	2528325 c0afedaf905c311c1fc91a55df92d1793f8f43 7f	no	2
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22	NPL Documents	16_BOHR_presentation_Intel_ISSCC_09_plenary.pdf	8968148 288c45398d711068a36020473b6c927da65 28428	no	66
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23	NPL Documents	17_PDF_BOHR_plenary_paper_Intel_ISSCC_09_pdf.pdf	1615786 eb378566ef634b46f17c05834bcae224a088 acc3	no	6
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24	NPL Documents	18_PDF_INGERLY_Low_K_Interconnect_IEEE_2008_pdf.pdf	651359 8e1a8daecb73909145098b76a9b7e881109 72a58	no	3
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25	NPL Documents	19_PDF_KURD_Next_generation_intel_2008_pdf.pdf	259226 19abd2c18c024cec75924c92bed9ec698a6 5fc4a	no	2
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26	NPL Documents	20_PDF_MALONEY_Novel_clamp_circuits_for_IC_power_supply_protection_pdf.pdf	191082 d68b46b342e836f0eda7955b62f727a63e 41cd7	no	12
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27	NPL Documents	21_PDF_GEFFKEN_Overview_of_polyimide_pdf.pdf	851514 e18b14453fb0b5d803d7a37663977c5306a b7dea	no	11
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28	NPL Documents	22_PDF_LUTHER_Planar_Copper_pdf.pdf	2095781 90afd29bd75e9d46783563e765b92e1c2d6 87a5a	no	8
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29	NPL Documents	23_PDF_MASTER_Ceramic_Ball_Grid_Array_pdf.pdf	1069512 bd6eeeaa156a9033c17b7766d18810a6d0f3 58a0b	no	5
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30	NPL Documents	24_PDF_MALONEY_Stacked_PMOS_clamps_for_high_voltage_power_supply_protection_pdf.pdf	1327621 bf7256b30d3890a26269a1501436f32580e bde88	no	8
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**Warnings:**

**Information:**

31	NPL Documents	25_PDF_LIN_A_New_System_On_Chip_Technology_pdf.pdf	390082 420f653caea0b51f8d8465f872b9a351e6fa 4296	no	7
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**Information:**

32	NPL Documents	26_PDF_MEGICA_Brochure_leaflets_01_28_04_pdf_pdf.pdf	888383 aec89db5e67eb17d33ea9f52144d8fbcb181f fd9a	no	3
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33	NPL Documents	27_PDF_LIN_Post_Passivation Technology_Presentation_for_ TSMC_Tech_Symposium_2003 _pdf.pdf	1277639 20556e2754a2807cec285bcc5d87f24d527 17e89	no	32
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**Warnings:**

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34	NPL Documents	28_PDF_LIN_A_New_IC_Interconnection_Scheme_and_Design_pdf.pdf	116206 e1e1d6bb5ccf0007c76b6677a40a8a47106 eecb8	no	4
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35	Fee Worksheet (PTO-875)	fee-info.pdf	32033 3a12e876aa6d8ac536754da55e9344f14c6c 9c82	no	2
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**Information:**

<b>Total Files Size (in bytes):</b>	41064693
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This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.

**New Applications Under 35 U.S.C. 111**

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

**National Stage of an International Application under 35 U.S.C. 371**

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

**New International Application Filed with the USPTO as a Receiving Office**

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.